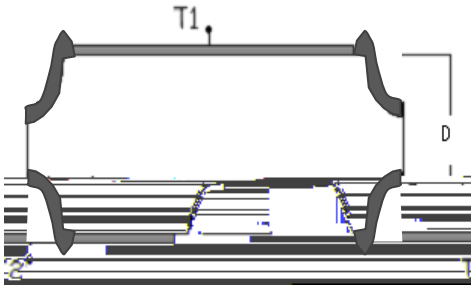
TVS

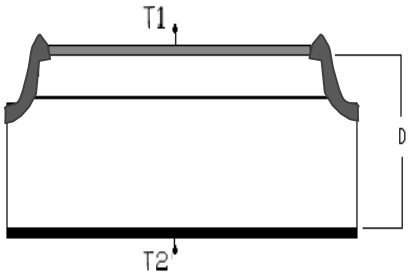
0->VBR 1ps

200W 10/1000μs

Wafer tech		
Wafer Size	Φ5inch	
Chip Thickness	D=265±15μm( )	
T1/T2 Metal	Front	TiNiAg
	Back	TiNiAg
Chip Size	(A: μm) Chip	1143±50
	(B: μm) Pad	848±25



1 TVS



2 TVS

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